

## Linear Low Density Polyethylene ML4400N

**Description:**

The resin ML4400N is a Linear Low Density Polyethylene developed for rotational molding

**Technical Characteristics:**

- Good surface finishing
- High stiffness
- Excellent processability
- UV radiation and heat stabilization

**Additives:**

- Weathering resistance UV8 and antioxidants

**Applications:**

Pigmented water tanks up to 3,000 L, Septic tanks

**Control Properties:**

Feature	Method	Units	Values
Melt Flow Rate (190°C/2.16kg)	D 1238	g/10 min	4.1
Density	D 792	g/cm <sup>3</sup>	0.939

**Typical Properties:**

Plaque properties

Feature	Method	Units	Values
Elongation at Yield (a)	D 638	%	13
Elongation at Break (a)	D 638	%	> 1000
Tensile Strength at Yield (a)	D 638	MPa	21
Flexural Modulus - 1% Secant (b)	D 790	MPa	670
Environmental Stress Cracking Resistance - Notch 0,3 mm; 50°C; 10% Igepal CO630 (a)	D 1693	h/F50	28
Environmental Stress Cracking Resistance - Notch 0,3 mm; 50°C; 100% Igepal CO630 (a)	D 1693	h/F50	300
Deflection Temperature under Load at 0,455 MPa (b)	D 648	°C	60
Deflection Temperature under Load at 1,82 MPa (b)	D 648	°C	40
Impact Strength - Thickness 3,17 mm (c)	ARM	J	40

Typical properties correspond to average values obtained in our laboratories. Test specimens prepared from compression molded sheet made according to ASTM D 4702. Thickness of test piece: a) 2 mm; b) 3 mm; c) Rotomolded plaque. Test temperature -40°C.

**Final Remarks:**

1. The information presented in this Data Sheet reflects typical values obtained in our laboratories, but should not be considered as absolute or as warranted values. Only the properties and values mentioned on the Certificate of Quality are considered as guarantee of the product.
2. For regulatory information of the product, please refer to Regulatory Document or contact our Technical Assistance Area.
3. For information about safety, handling, individual protection, first aids and waste disposal, please refer to MSDS.
4. The mentioned values in this report can be changed at any moment without Braskem previous communication.